

## 2 CHANNEL VOLTAGE SENSE AMR/GMR PREAMPLIFIERS

**PRODUCT PREVIEW** 

- Power Supplies +5Vdc, +8Vdc
- Current bias or voltage bias (selectable) / Voltage sense architecture
- Single ended read input
- 24 pin TSSOP package, two channels
- External Resistor for read and write currents or trimmed internal resistor available (serial port selectable)
- Read channel -3dB bandwidth > 300MHz (Rmr=60 ohms, no interconnect)
- Input equivalent preamplifier voltage noise 0.5nV/rtHz typ
- Input equivalent MR bias current noise 10pA/rtHz tvp
- MR bias current programmable (5 bit DAC) 1.8-8mA (GMR range), 3.8-10mA (AMR range)
- MR bias voltage programmable (5 bit DAC) 100-460mV (GMR range), 220-580mV (AMR range)
- Programmable gain (100V and 150V)
- Write frequency up to 250MHz (Lh=90nH,R=15 ohms, Ch=2pF, VDD=8V)
- Rise/Fall time <0.7ns (lw =40mA 0-pk, Lh=90nH, Rh=15 ohms, Ch=2pF, VDD=8V)
- Write current programmable (5 bit DAC) 15-60mA
- Overshoot control 3 bit resolution (+1 bit for range)
- Bi-directional 16-bit TTLs Serial interface for head selection, read/write currents selection, chip parameters modification, chip enable, vendor code and fault status read back registers
- 2-wire mode selection (R/W, MRR)
- Bank write feature for servo write
- Digital buffered head voltage DBHV / Analog buffered head voltage ABHV pin (gain 5)
- Thermal asperity detection with adjustable sensitivity level (6 bit DAC)
- Thermal asperity correction
- Read head open/short detection
- Low supply detect and temperature monitoring (high temperature warning and Analog Temperature
- Diode Voltage measurement)
- Low write frequency detection
- WRITE to READ fast recovery 250ns (same head, including 150ns blanking period)
- GMR Low-Bias in WRITE mode with fast



recovery to READ mode bias (250ns)

- Head-to-head switch in READ mode 10µs (typ)
- Head and MR bias current switching transient current head protection
- READ-to-WRITE switching 30ns (same head)
- Programmable read bias during write and bank write operation
- ESD diodes for GMR protections
- Differential Write Driver to minimize coupling to GMR element

## **DESCRIPTION**

The L6326 is a two channel BICMOS monolithic integrated circuit GMR pre-amplifier designed for use with four-terminal magneto-resistive (AMR and GMR heads) read/inductive write heads. The device consists of a voltage sense current bias or voltage bias (selectable), single ended input/ true differential output (RDX, RDY), low-noise high bandwidth read amplifier and includes fast current switching write drivers which support data rates up to 500 Mb/s with 90nH write heads.

The GMR pre-amplifier provides programmable read current/voltage bias and write current (5 bit DACs), fault detection circuitry and servo writing features. Read amplifier gain, write current wave shape (overshoot and damping) can be adjusted and a thermal asperity detection and correction circuit can be enabled and programmed with different thresholds (6 bit DAC) through a 16-bit bi-directional serial interface (SDEN, SDATA, SCLK). The device operates from a +5V supply and a +8V supply (typical) for the write drivers. No external components are required if the internal trimmed resistor for reference current setting is selected.

Figure 1. Preamplifier block diagram VCC (+5V) VGND (0V) VDD (+8V) HW0X WDX PREDRIVER HW0Y WDY WRITE **DRIVERS** FAULT PROCESSOR Low supply detection, Open/short heads, FLT TA detection, low write frequency, HW1X high temperature HW1Y **SDATA** Rdamp Overshoot WRITE DAC SERIAL INTERFACE CONTROL SCLK SDEN Imr, Iwr RW enable current/voltage low bias head select READ R/W DAC HEAD SELECTION MODE CONTROL ABHV, MR meas MRR HR0 Temperature monitoring ABHV/ MR **ADTV** TA detection, **READ** TA correction **INPUT** RDX **STAGES RDY** HR 1 Gain boost **VREF** L6326

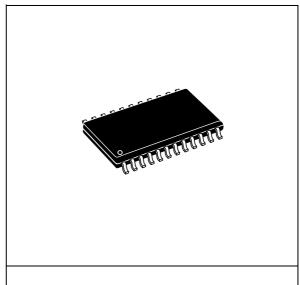
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**HGND** 

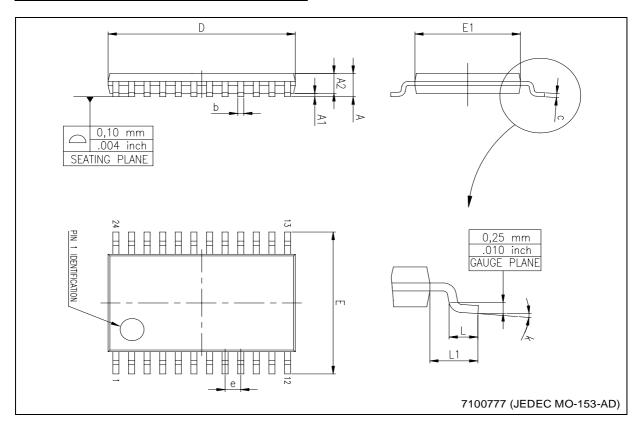
**47/** 

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
Α			1.20			0.047
A1	0.05		0.15	0.002		0.006
A2	0.80	1.00	1.05	0.031	0.039	0.041
b	0.19		0.30	0.007		0.012
С	0.09		0.20	0.003		0.008
D	7.70	7.80	7.90	0.303	0.307	0.311
Е		6.40			0.252	
E1	4.30	4.40	4.50	0.170	0.173	0.177
е		0.65			0.025	
L	0.45	0.60	0.75	0.018	0.024	0.030
L1		1.00			0.039	
k	0° min., 8° max.					

## OUTLINE AND MECHANICAL DATA



TSSOP24
Thin Shrink Small Outline Package



47/

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47/